

FIG. 1

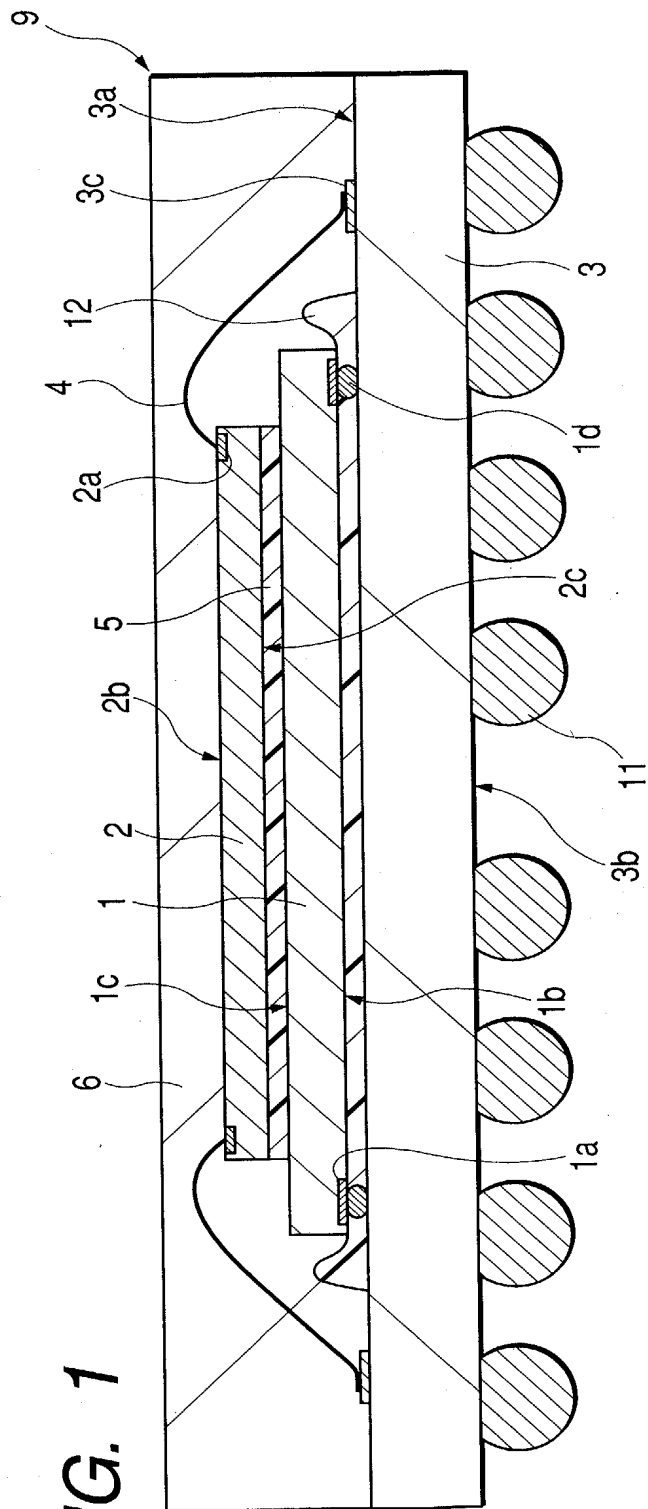


FIG. 2

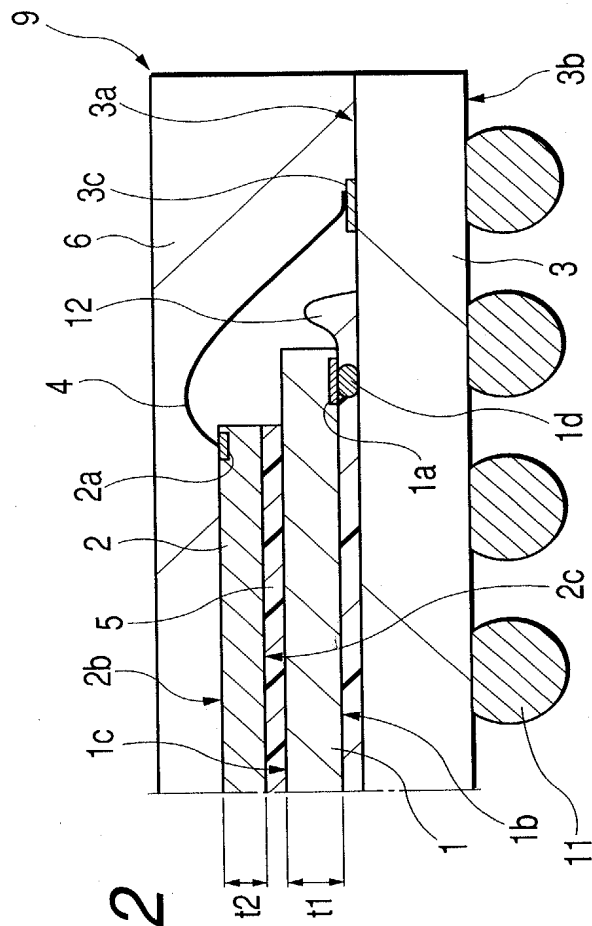


FIG. 3

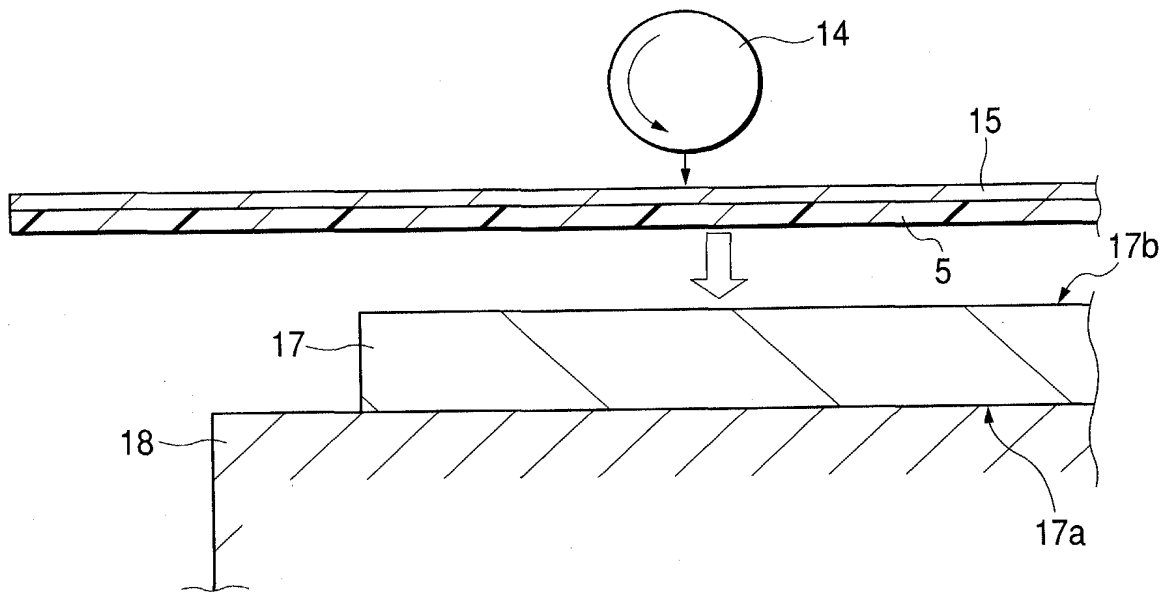


FIG. 4

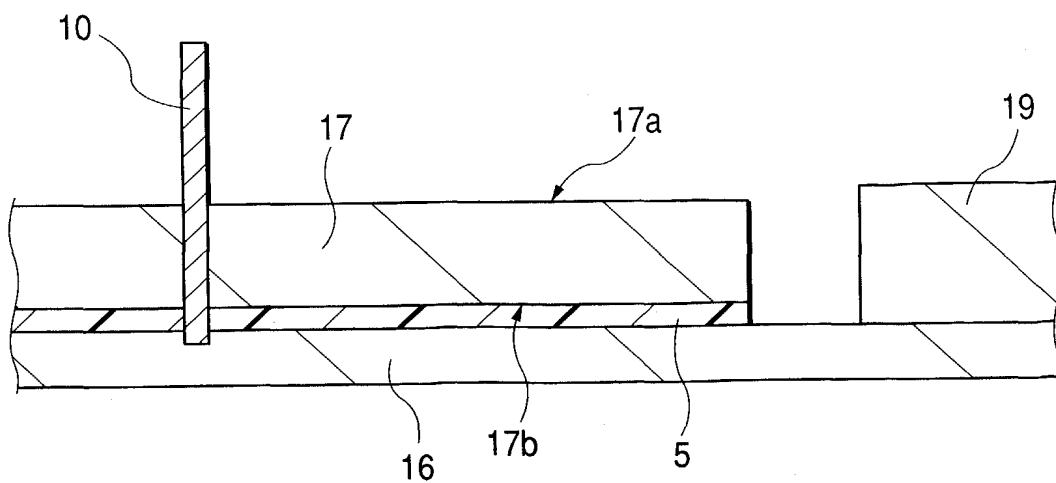


FIG. 5(a)

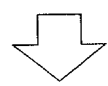
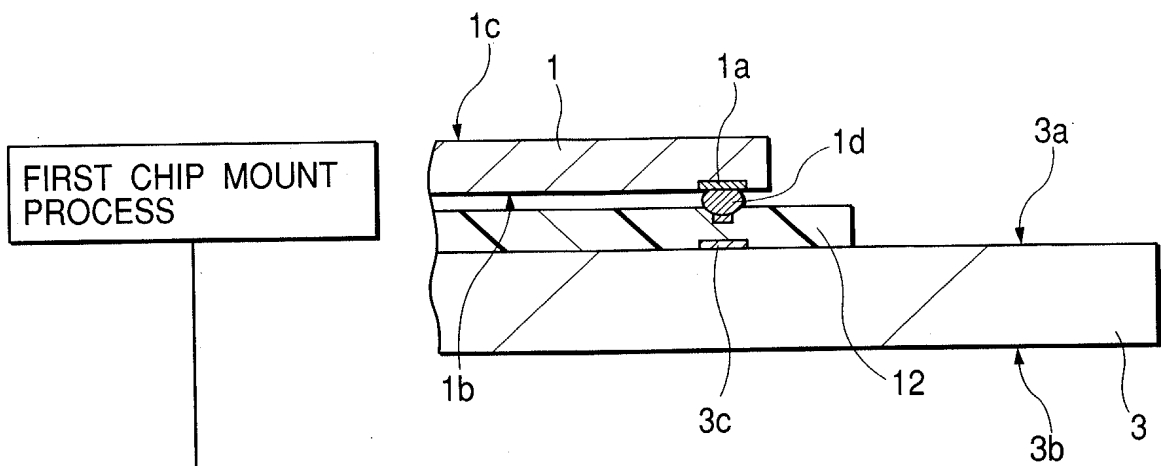
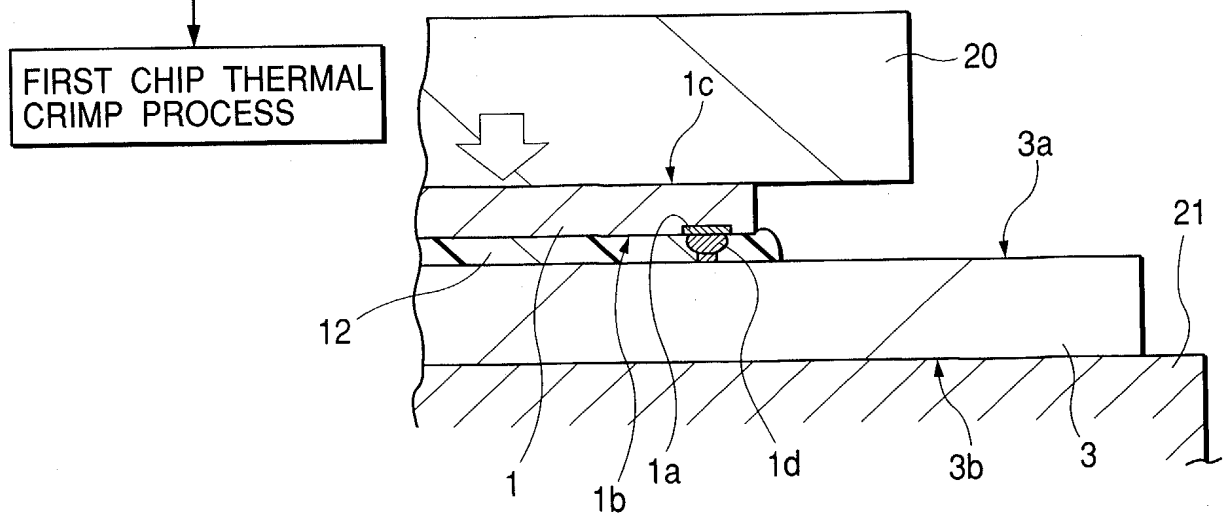


FIG. 5(b)



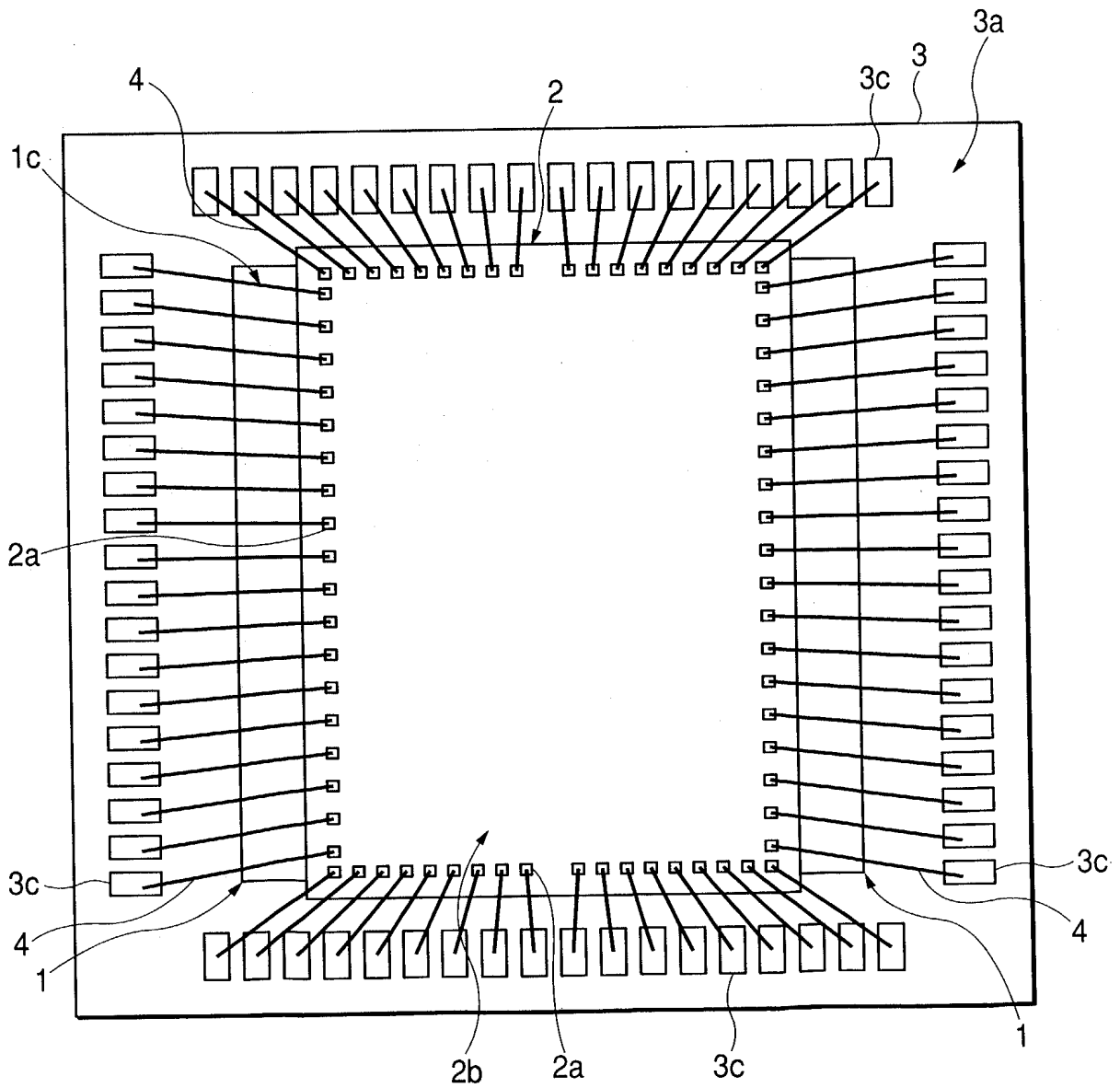
20240001429001

[illegible]

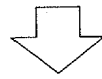
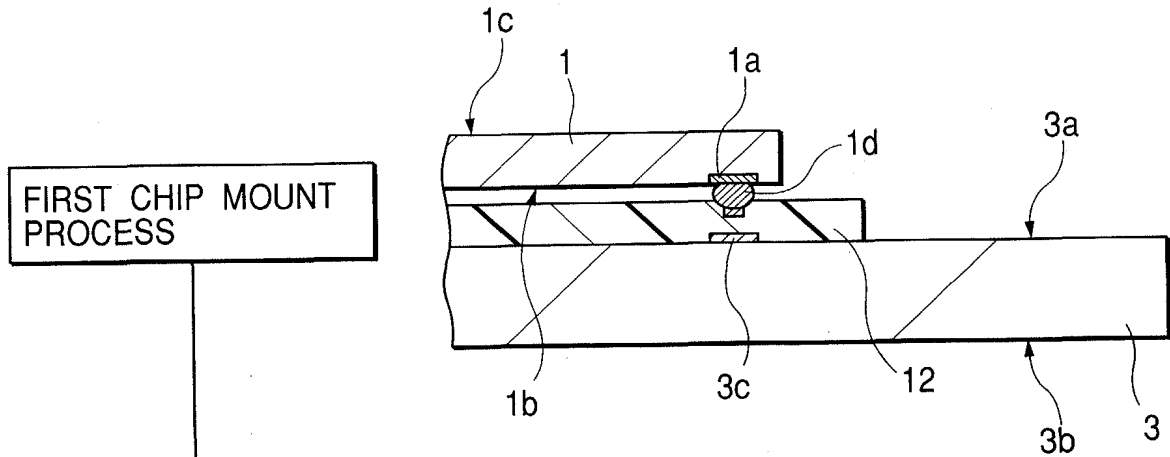
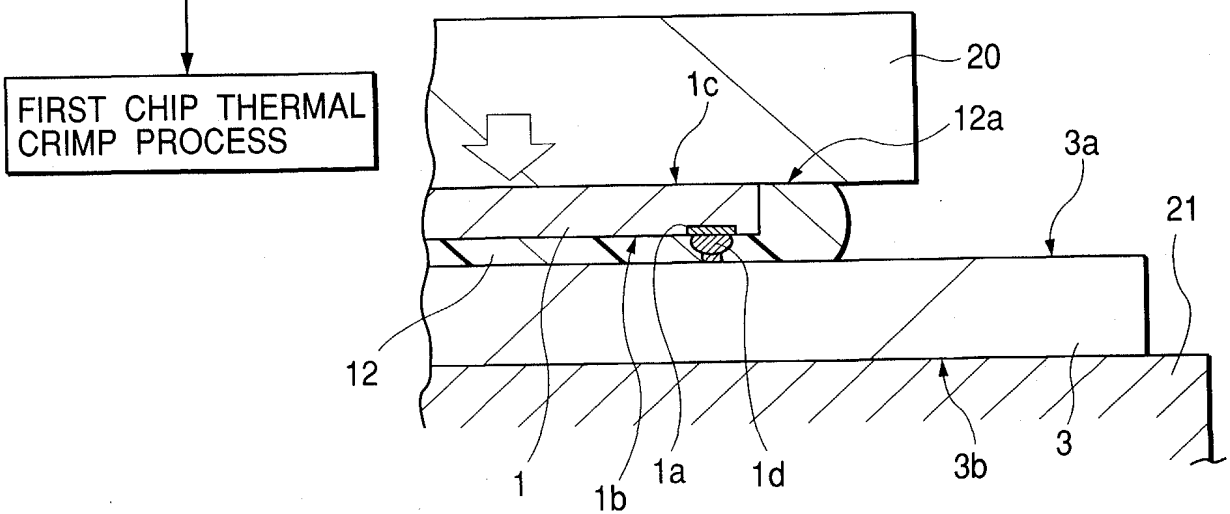
WIRE BOND PROCESS

[illegible]

FIG. 8



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FIG. 9(a)**FIG. 9(b)**

SECOND CHIP MOUNT PROCESS

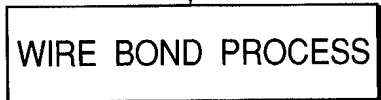


FIG. 11

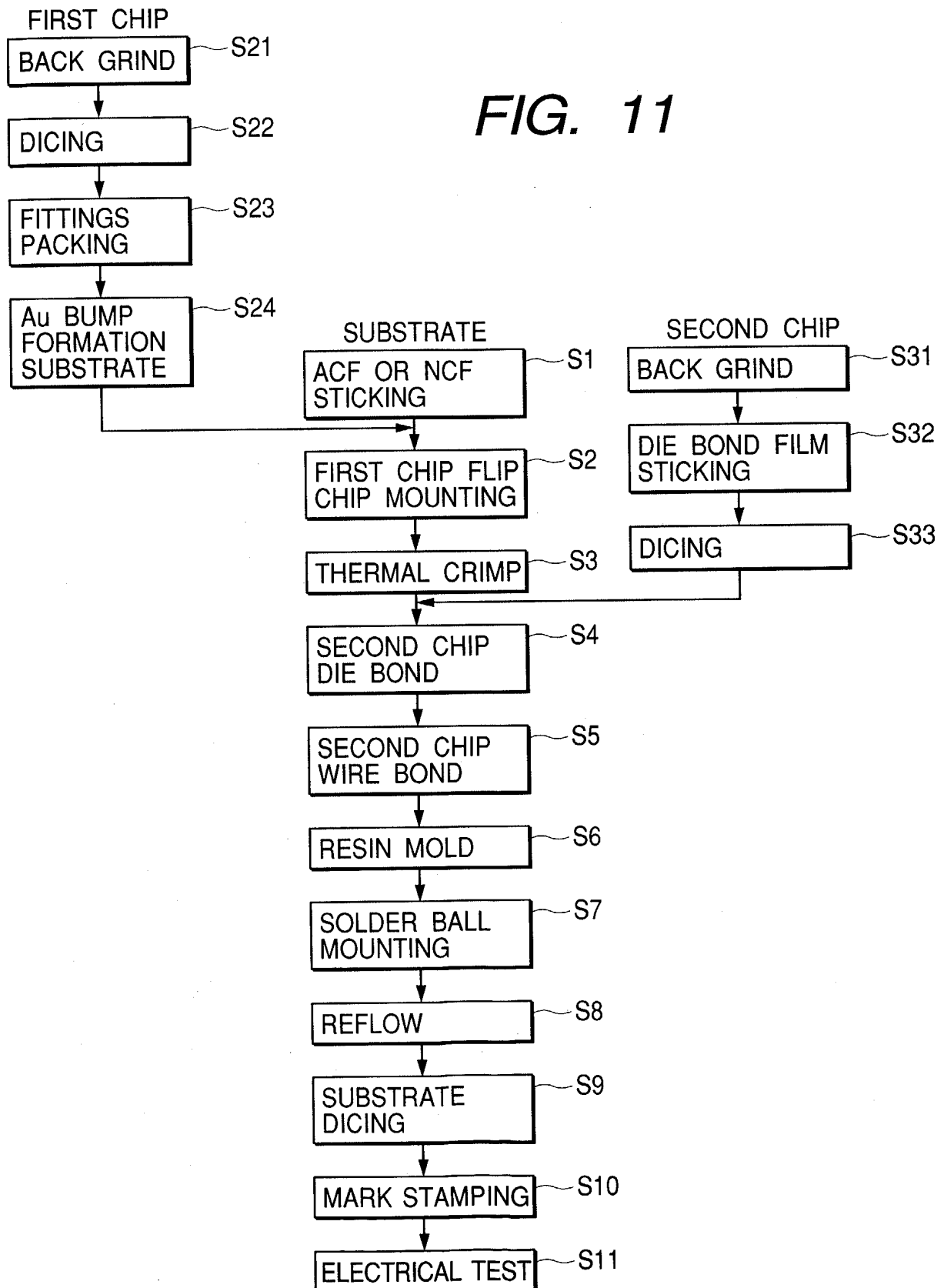


FIG. 12

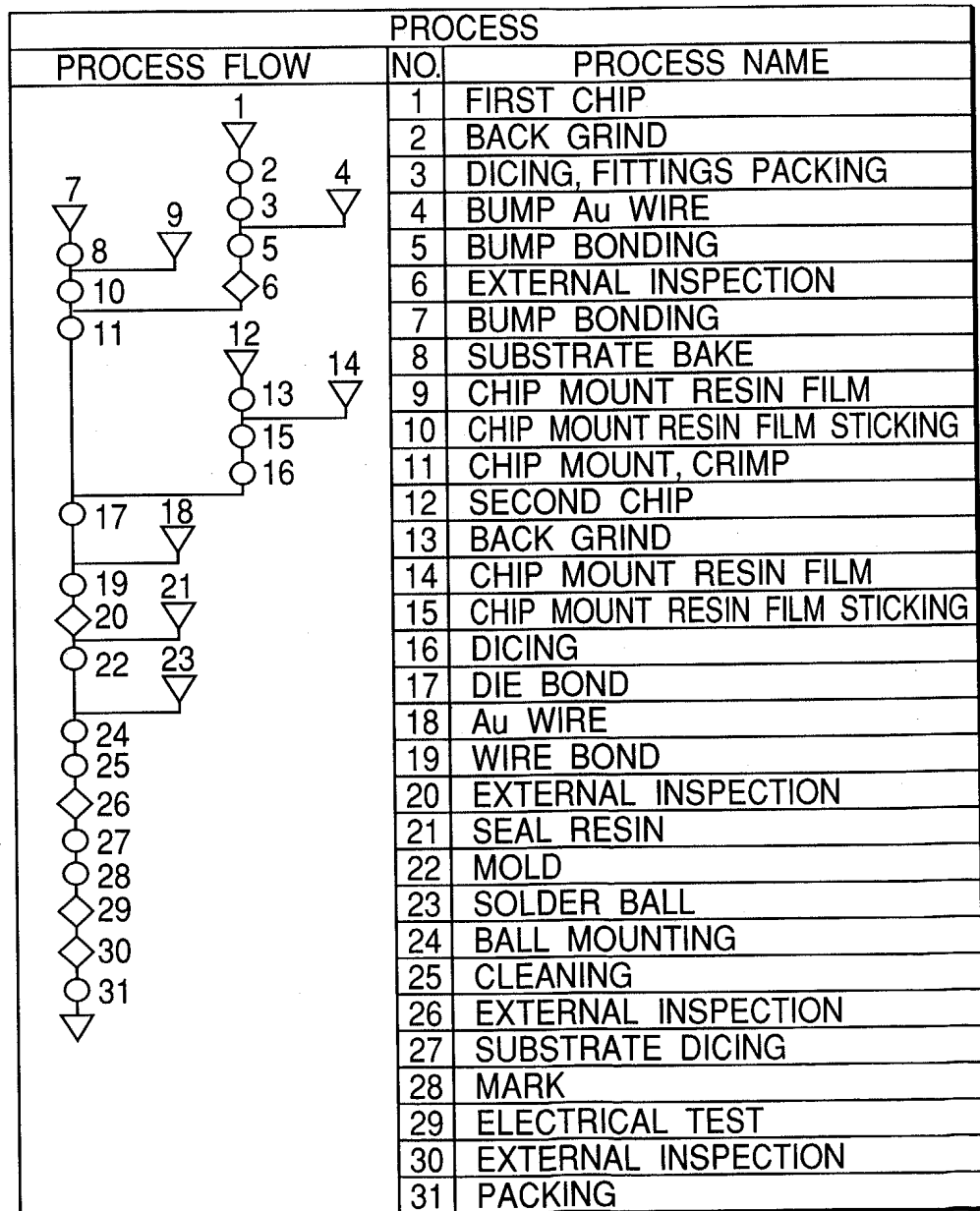


FIG. 13

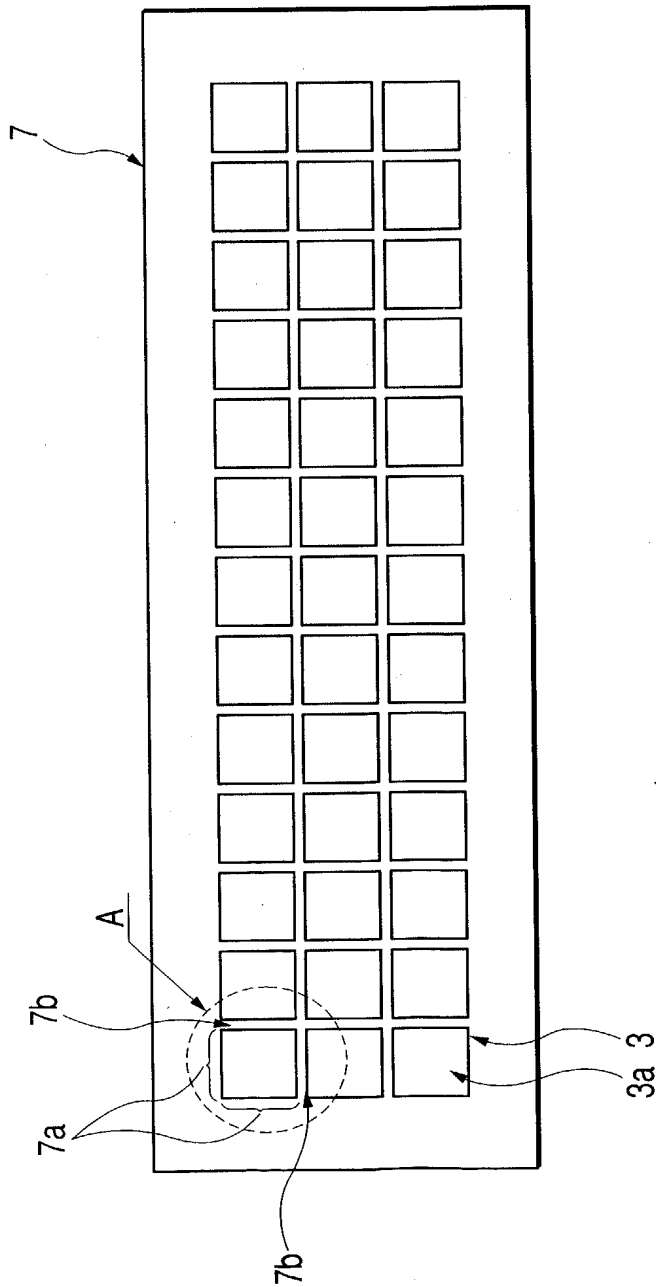


FIG. 14(a)

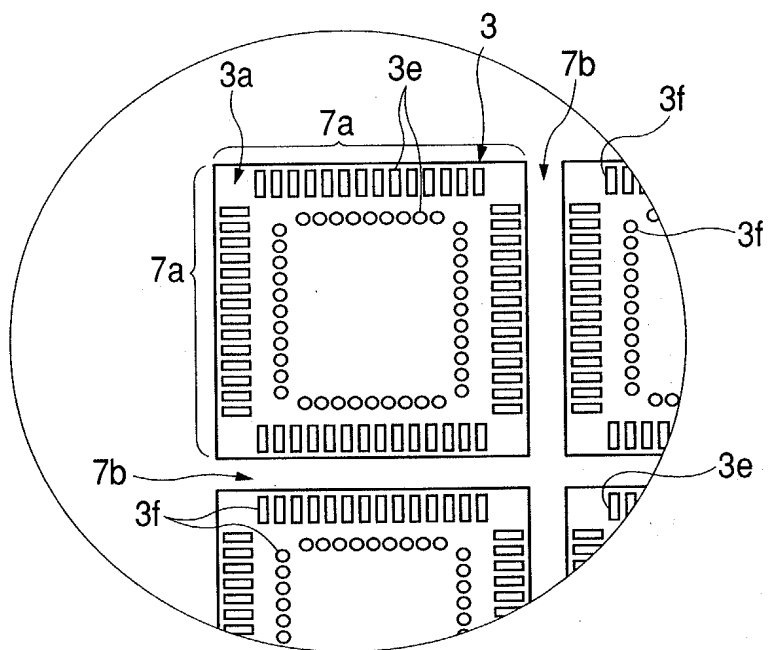


FIG. 14(b)

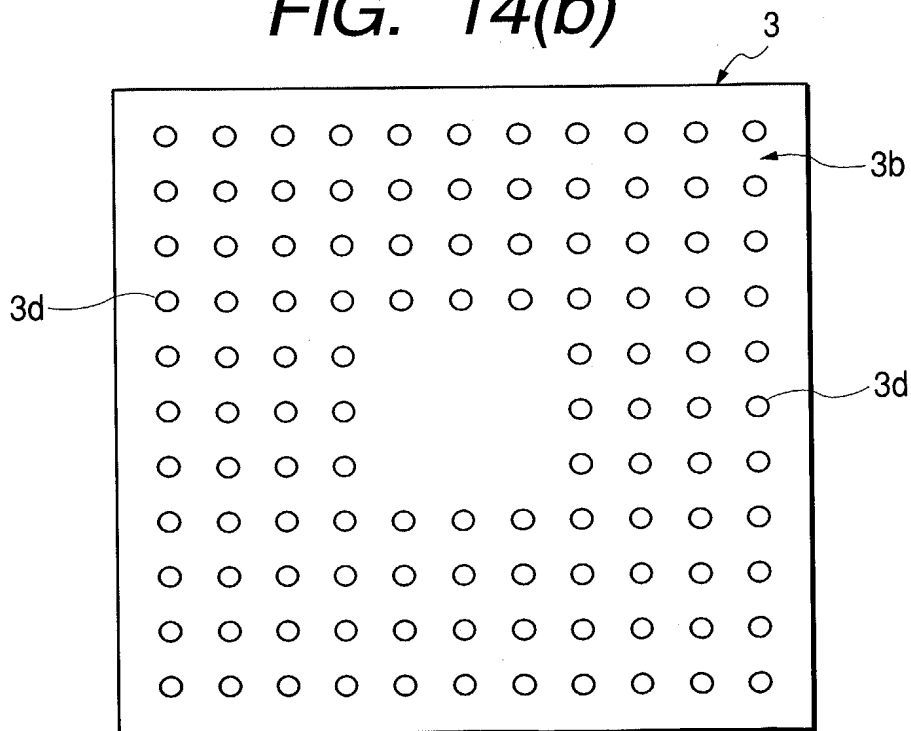


FIG. 15(a)

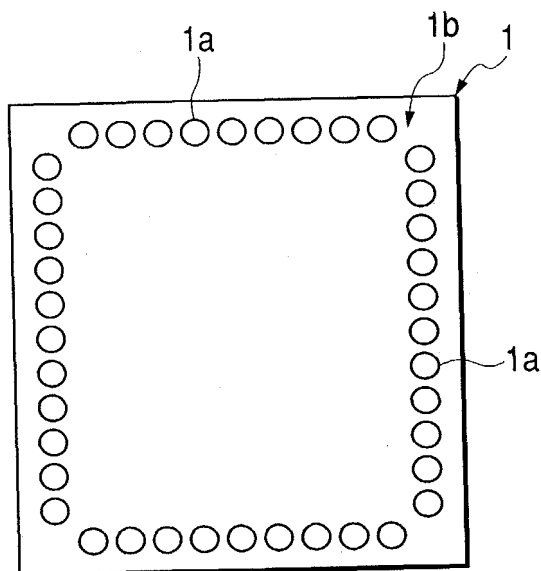
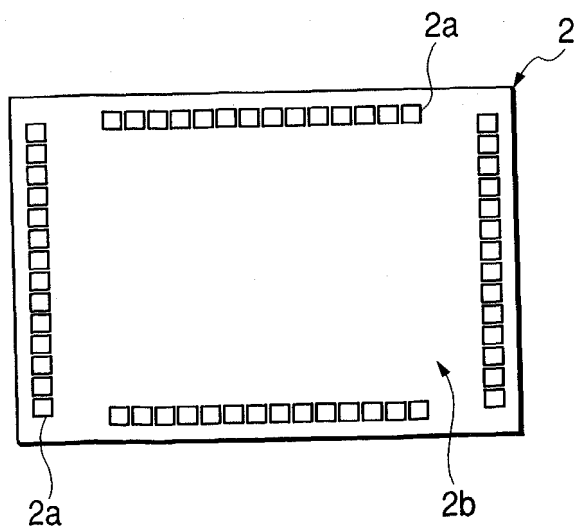


FIG. 15(b)



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FIG. 16(a)

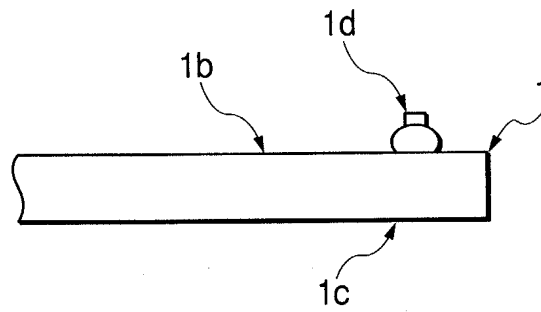


FIG. 16(b)

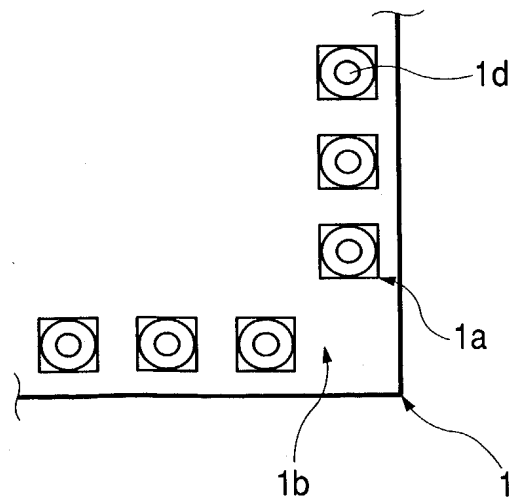


FIG. 17

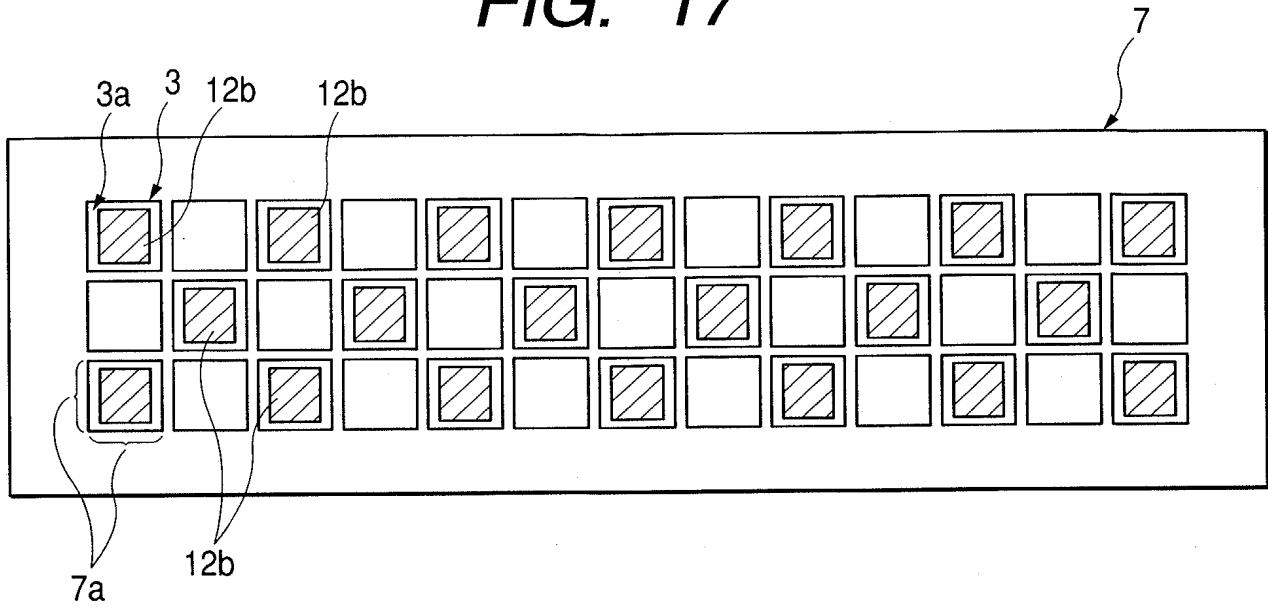


FIG. 18(a)

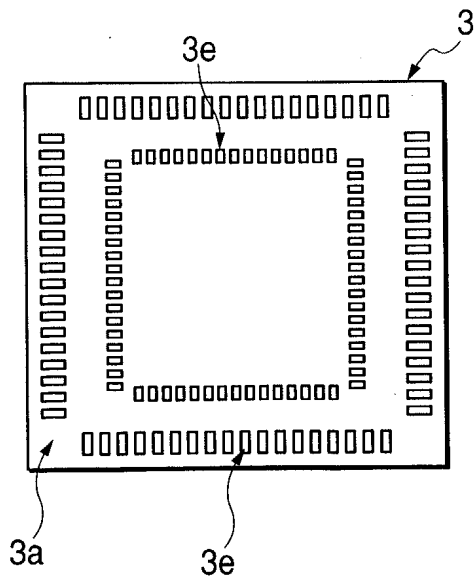


FIG. 18(b)

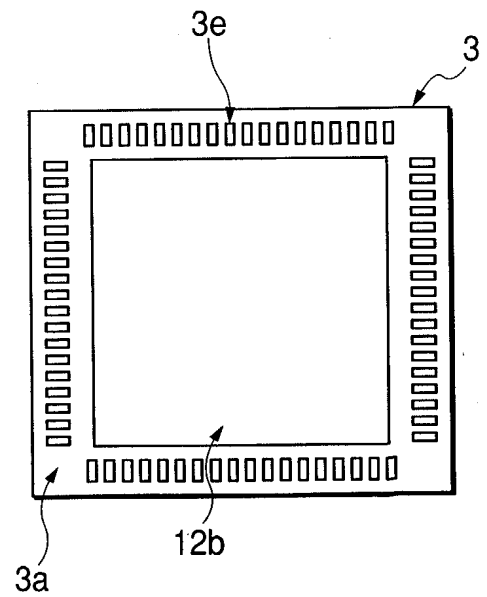


FIG. 19(a)

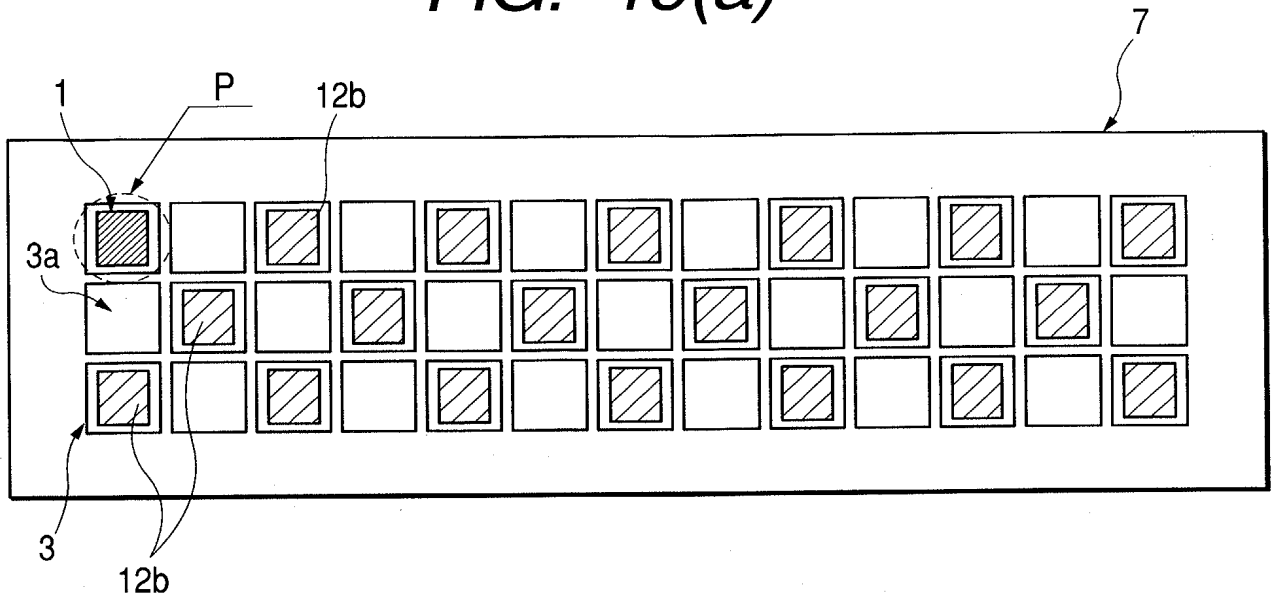


FIG. 19(b)

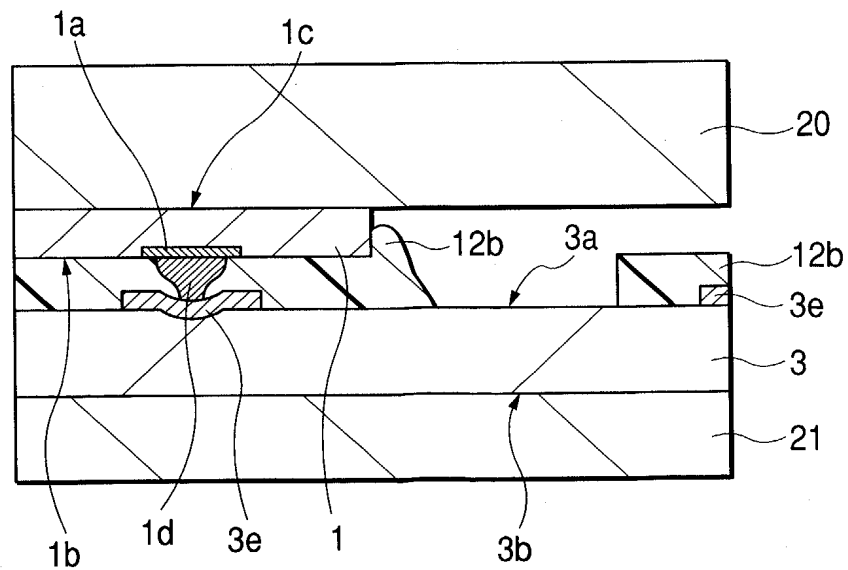


FIG. 20(a)

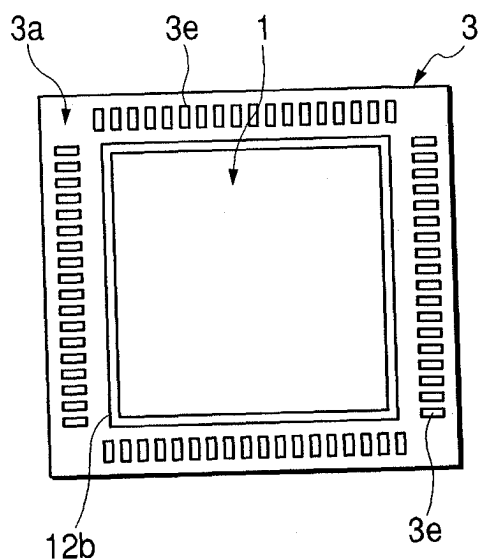


FIG. 20(b)

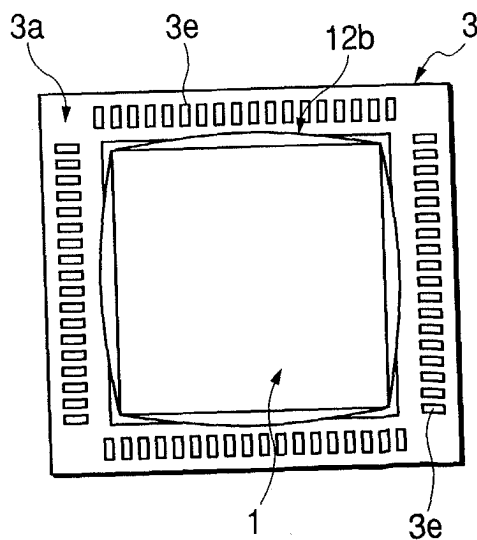


FIG. 22

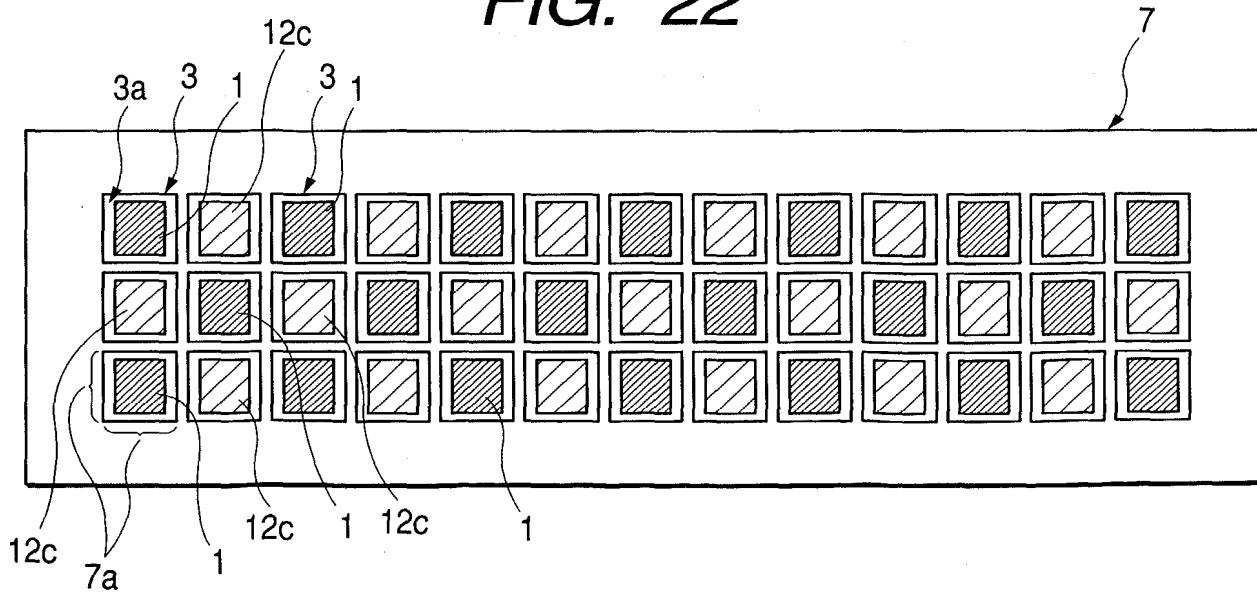


FIG. 23(a)

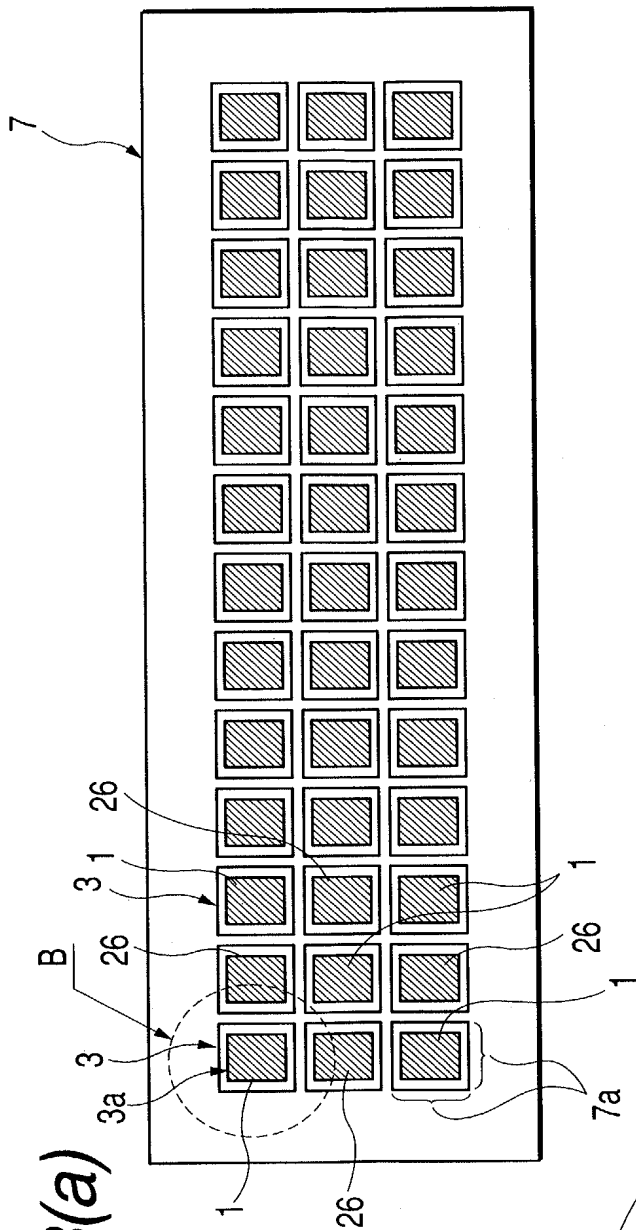


FIG. 23(b)

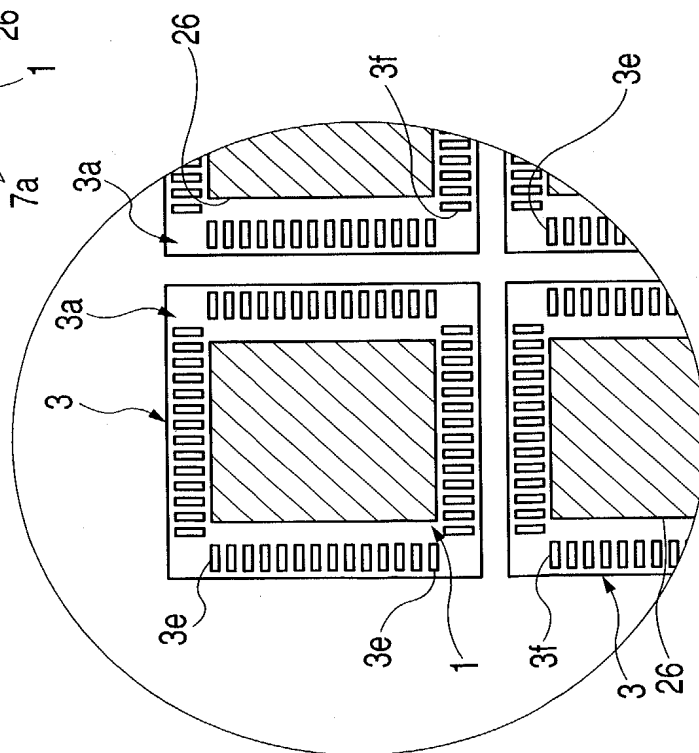
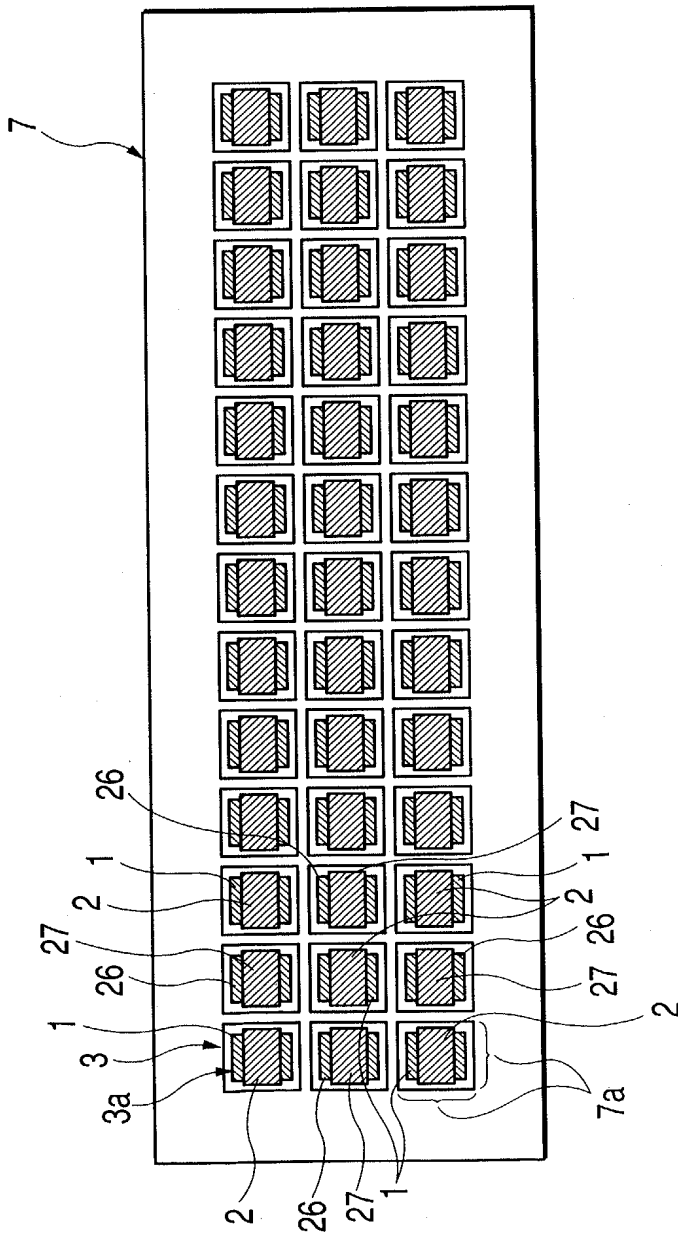


FIG. 24



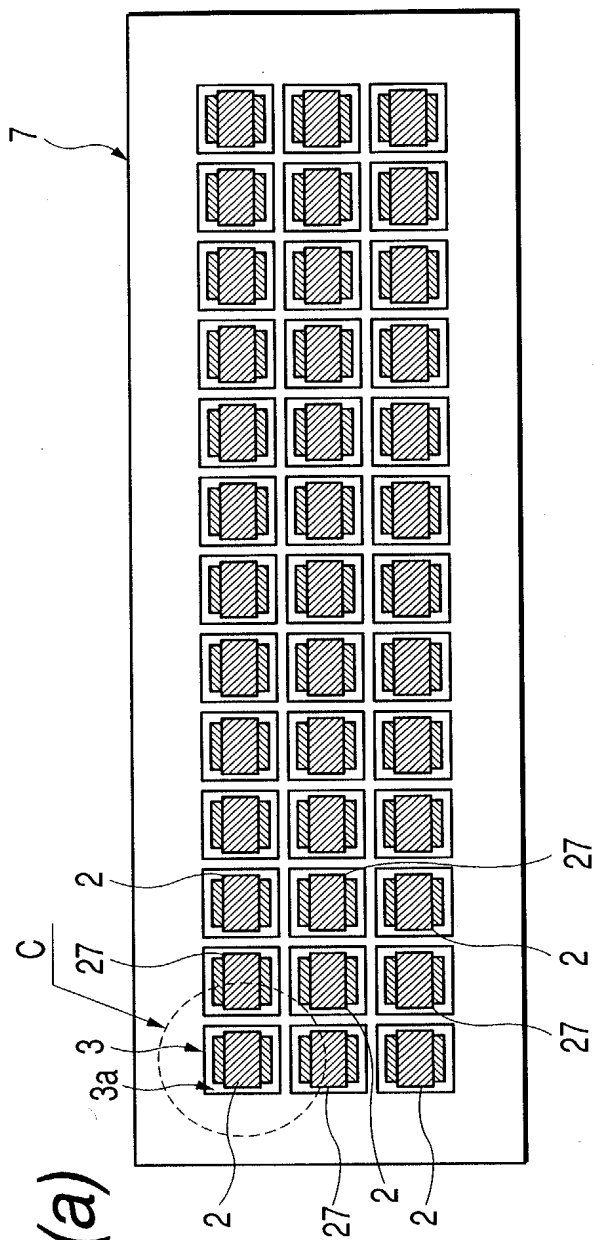


FIG. 25(a)

FIG. 25(b)

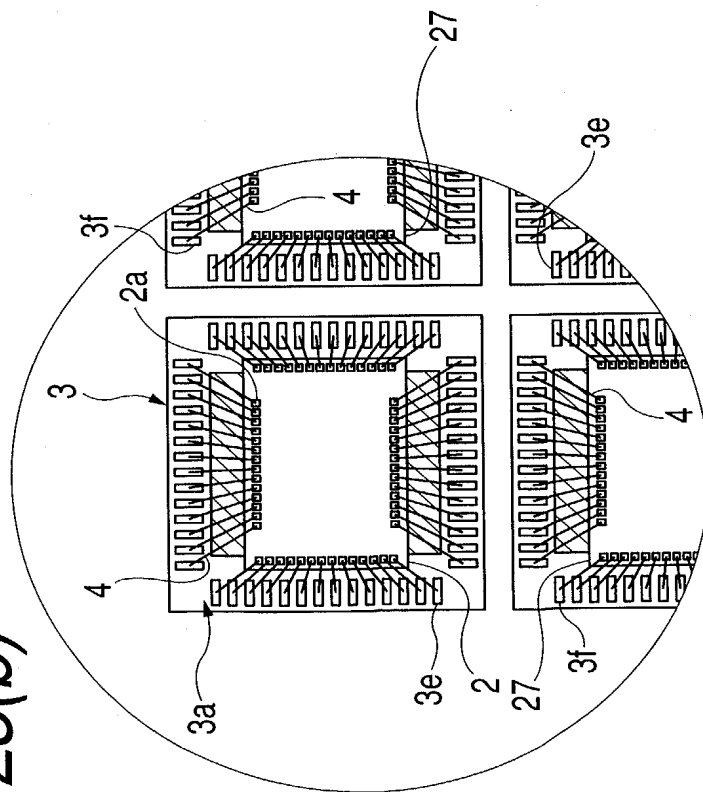


FIG. 26(a)

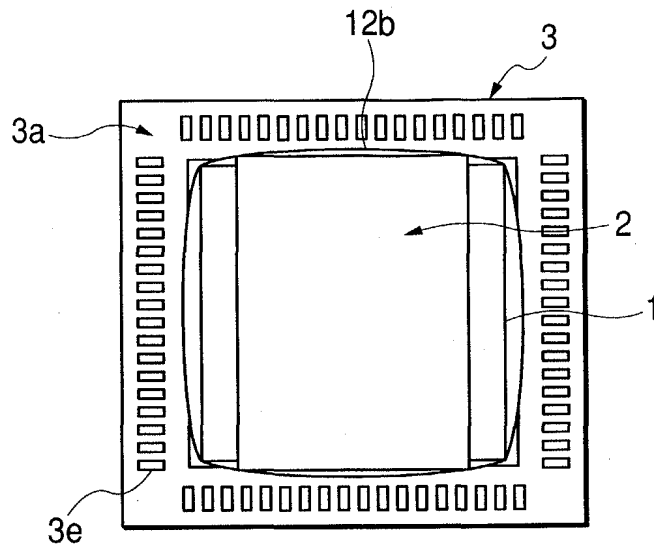
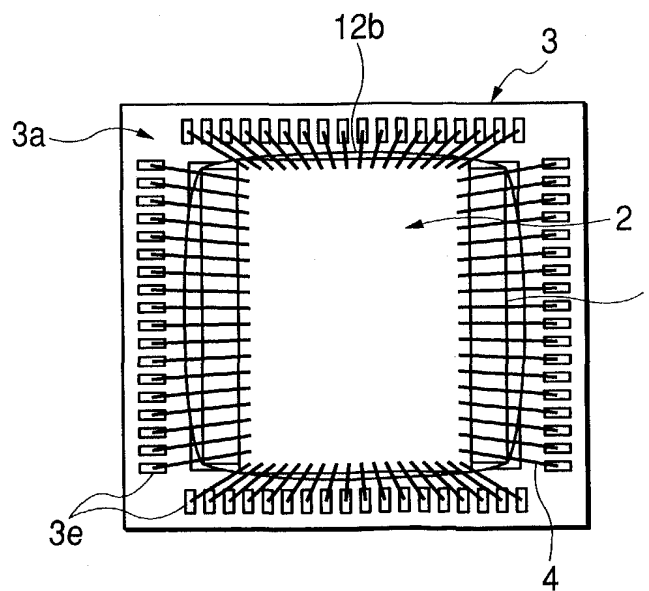


FIG. 26(b)



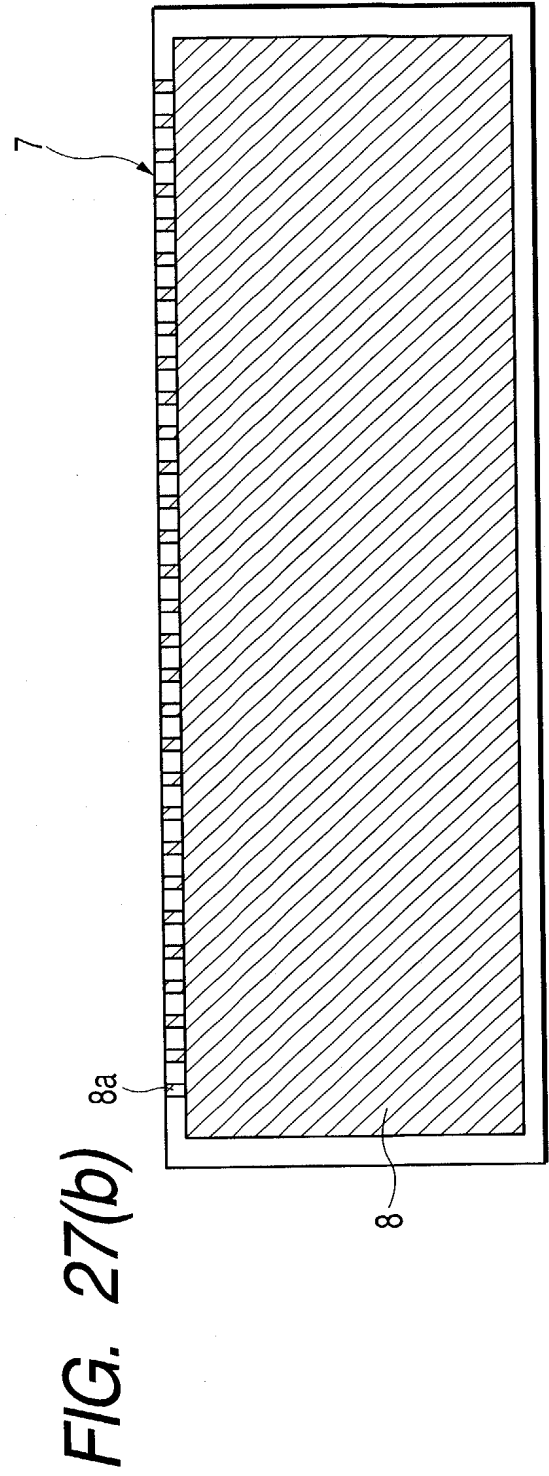
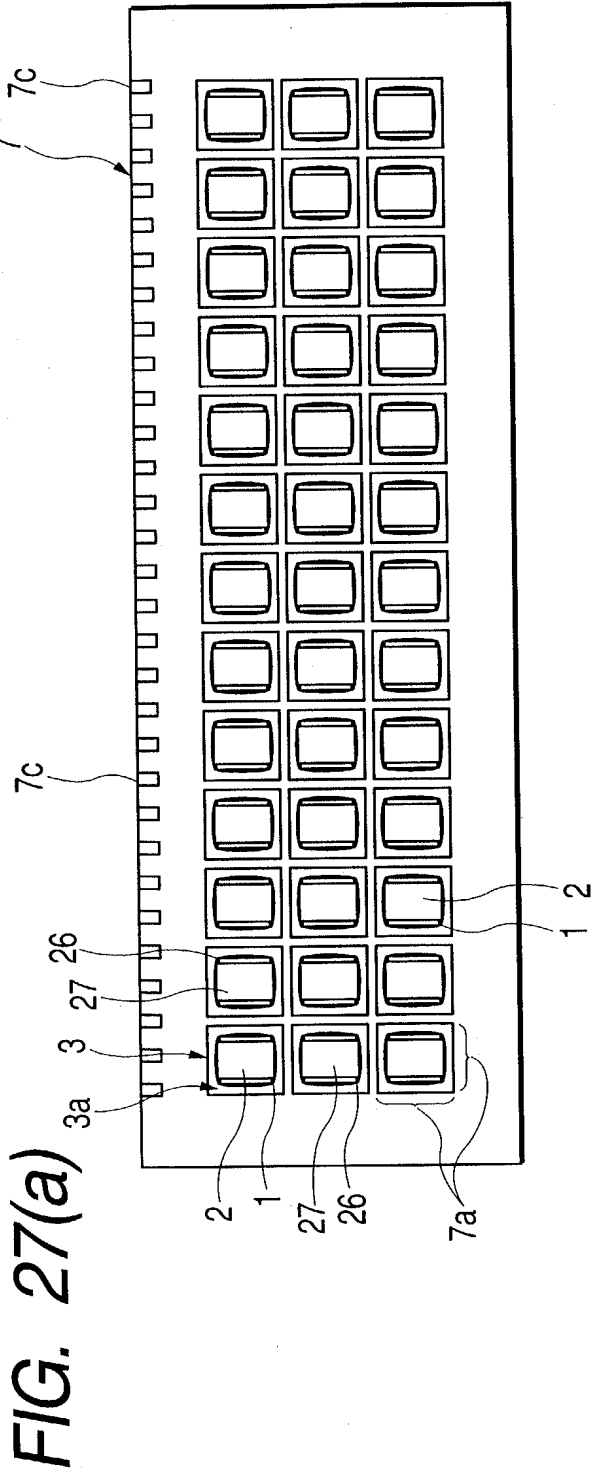
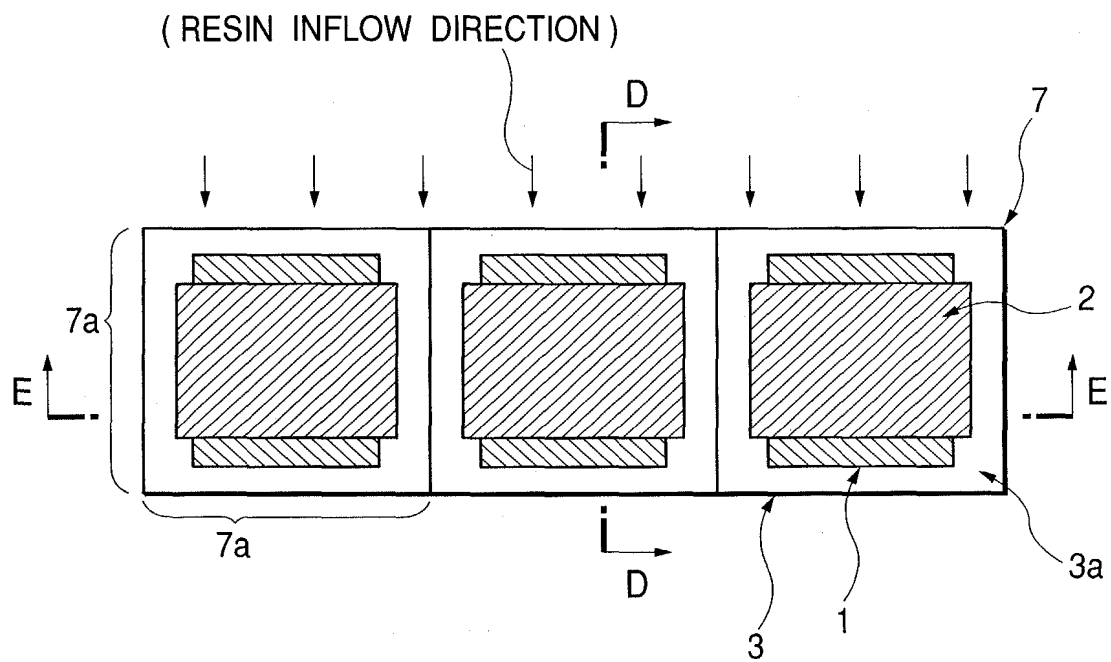


FIG. 28



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FIG. 29(b)

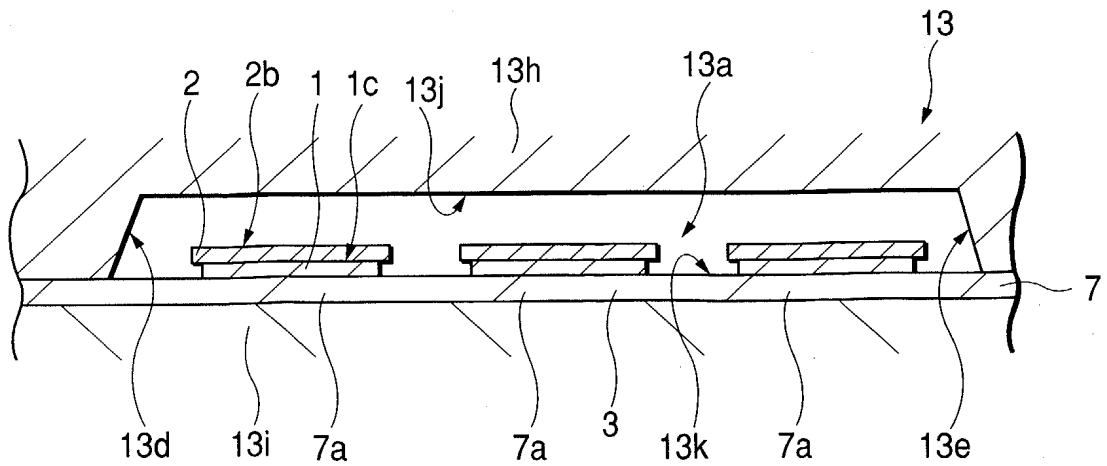


FIG. 30

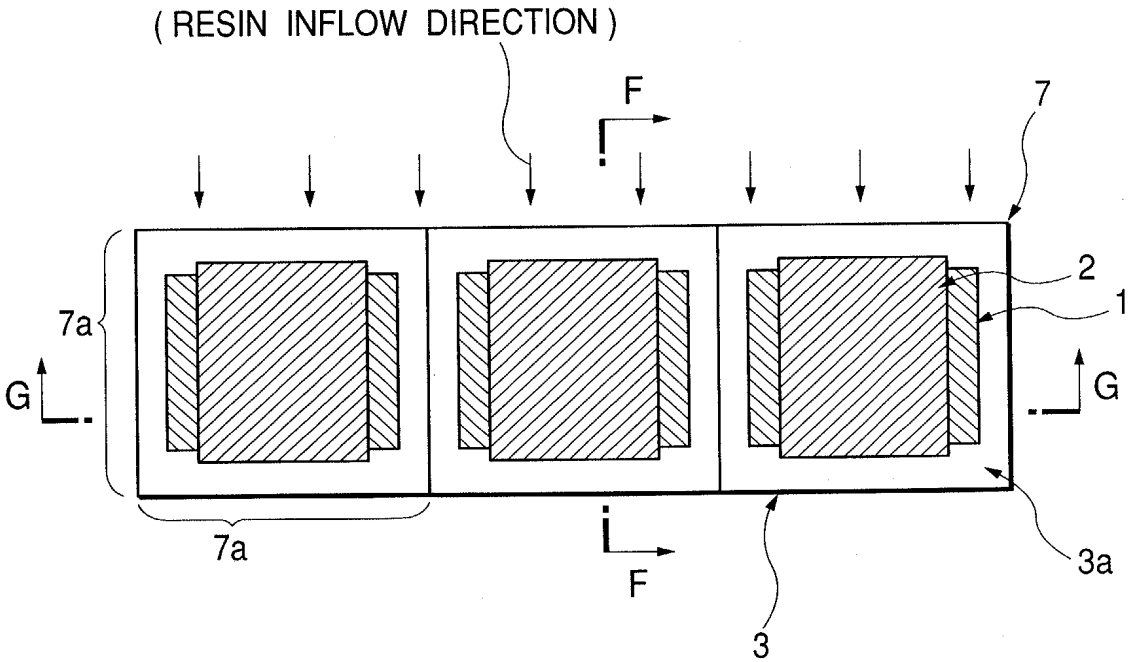


FIG. 31(a)

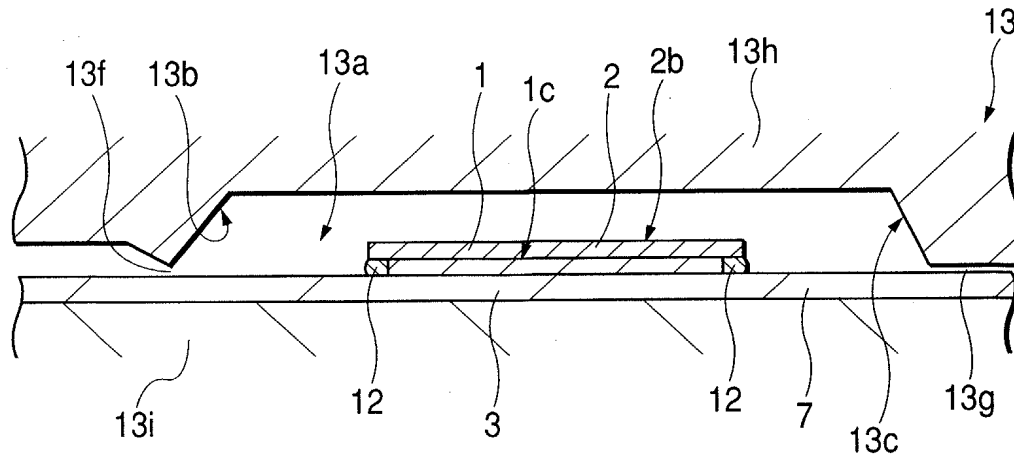


FIG. 31(b)

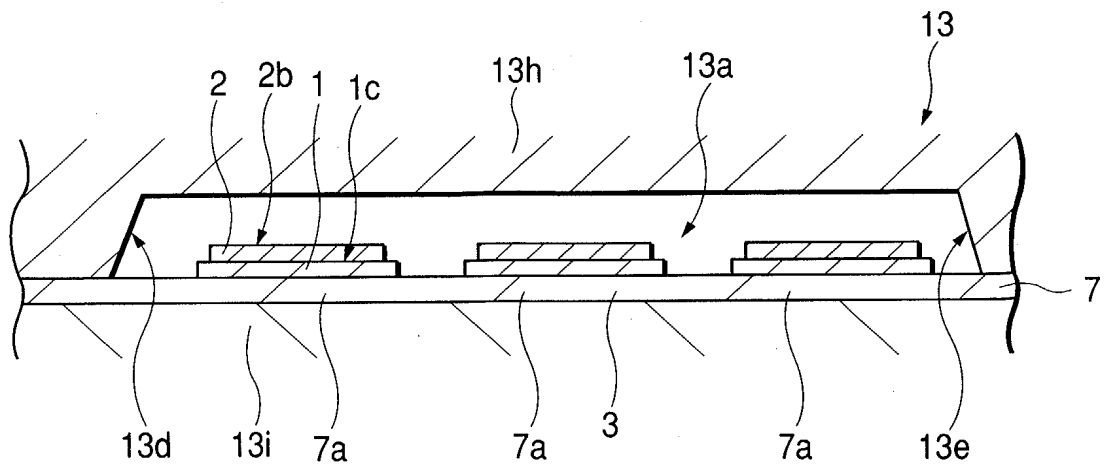


FIG. 32

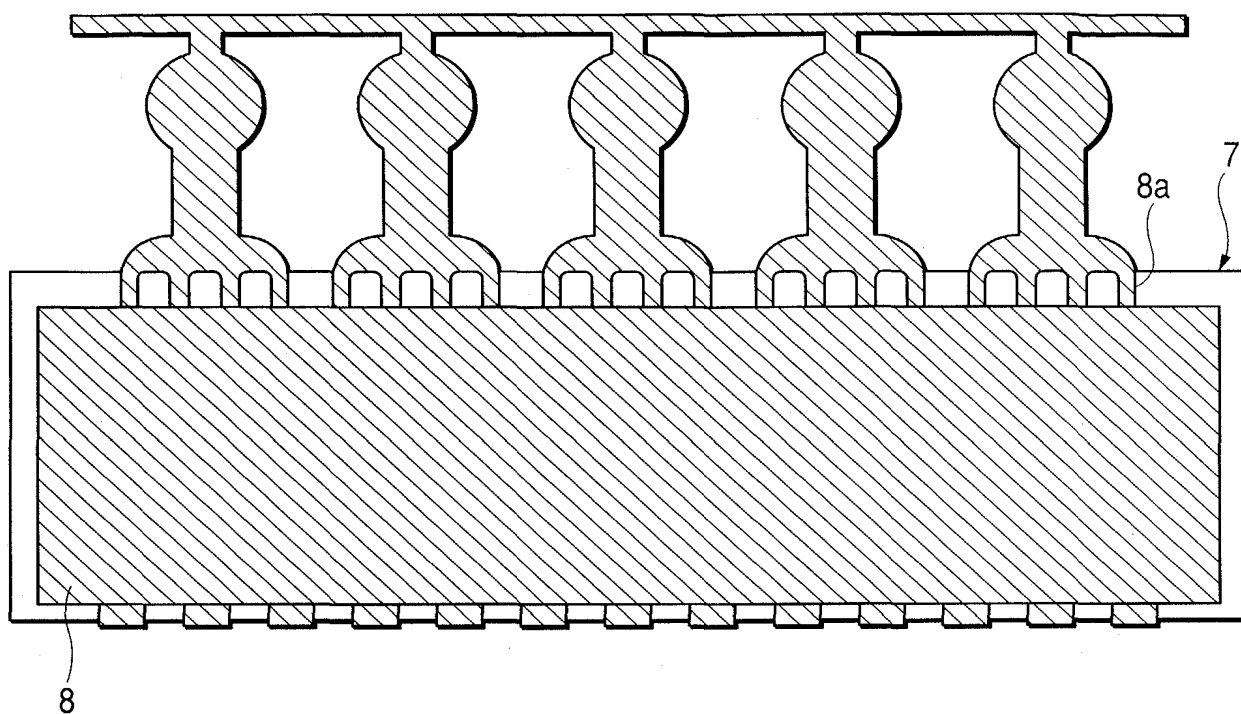


FIG. 33

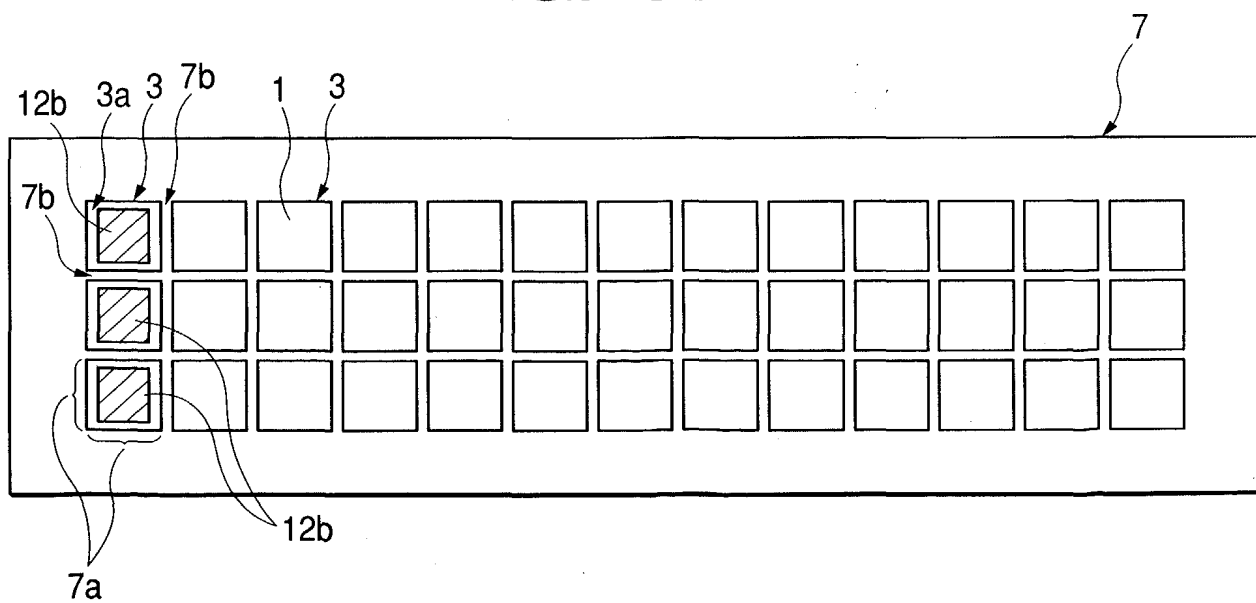


FIG. 34

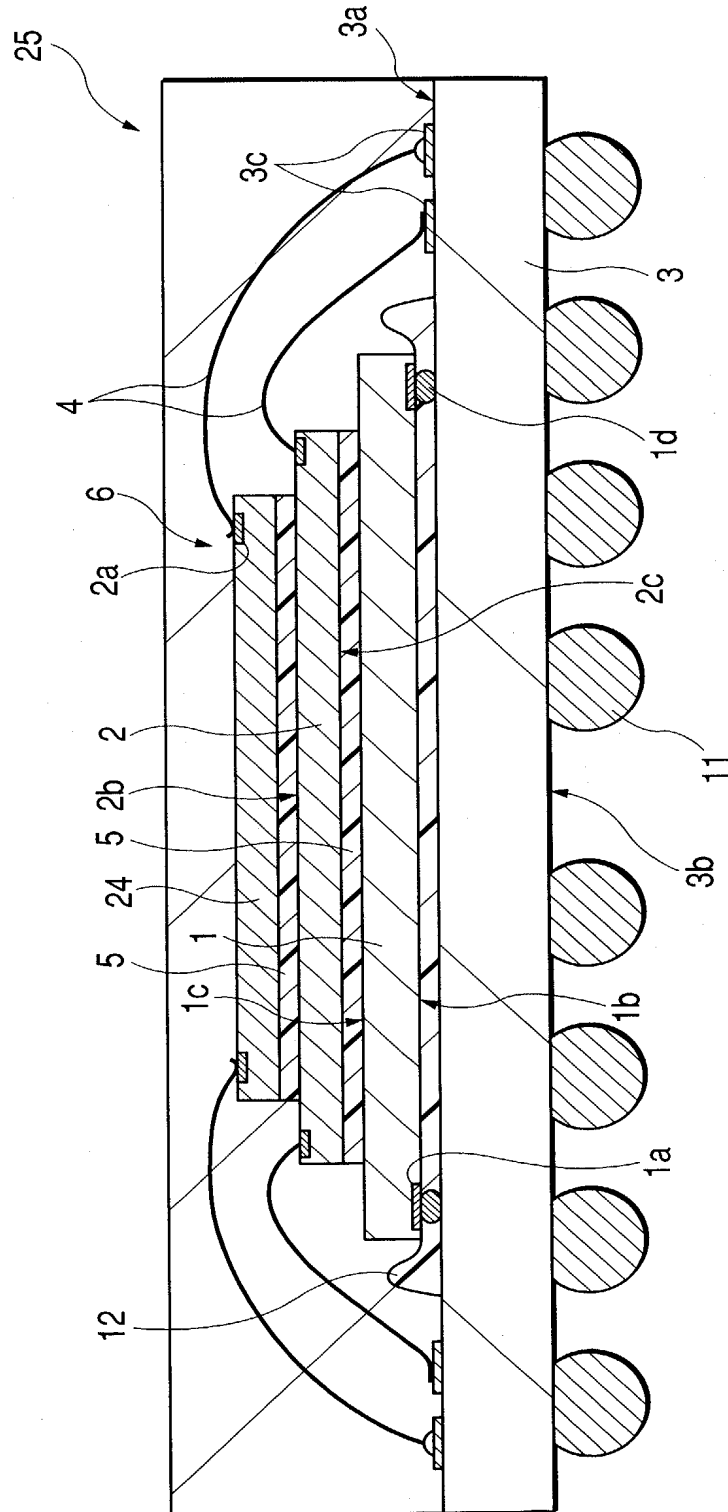


FIG. 35

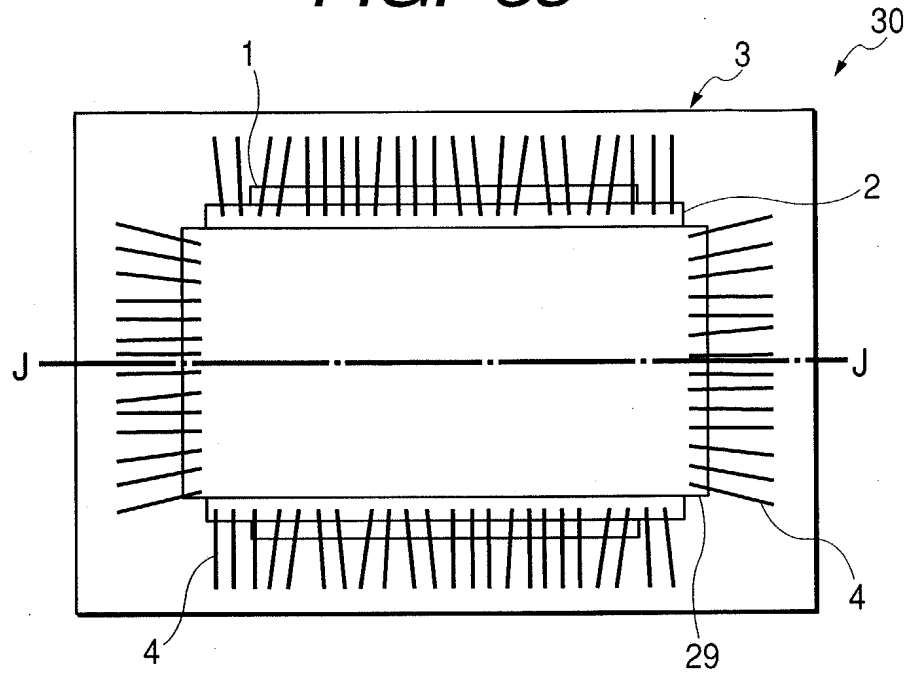


FIG. 36

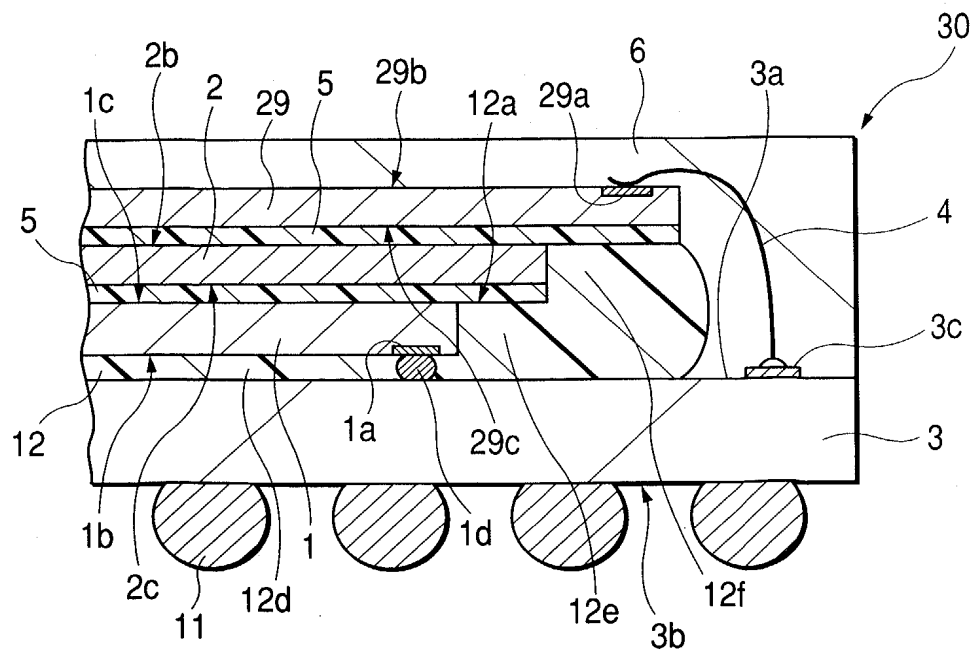


FIG. 37

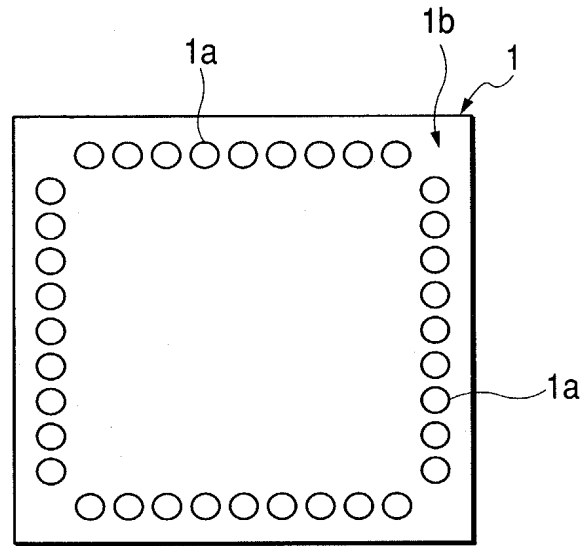


FIG. 38

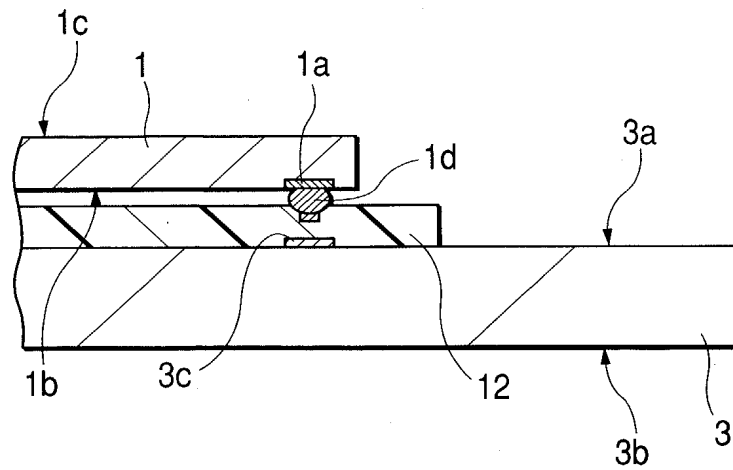


FIG. 39

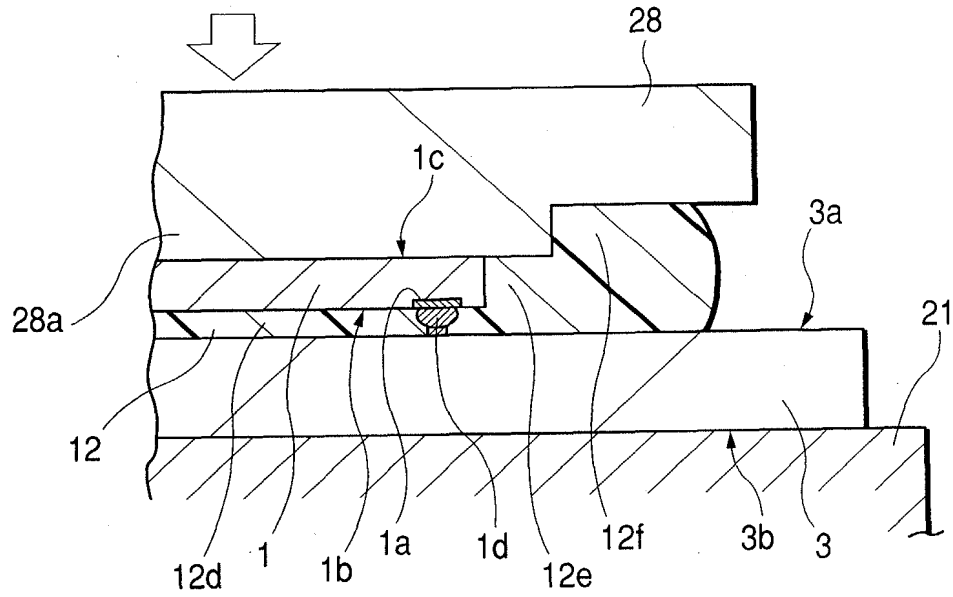
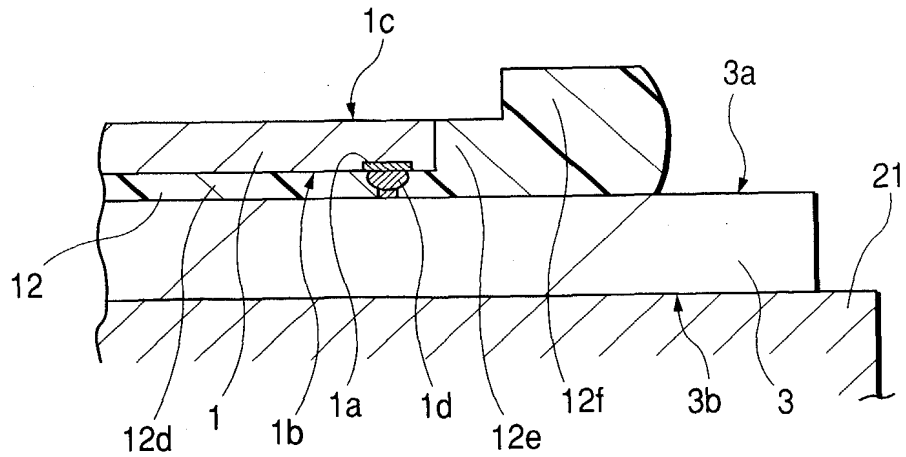


FIG. 40



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FIG. 41

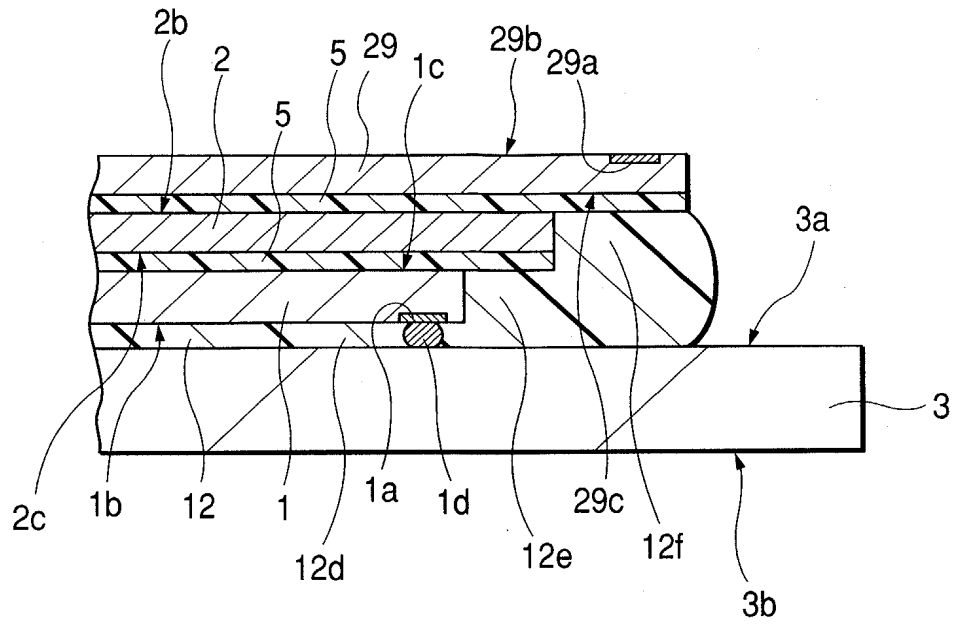


FIG. 42

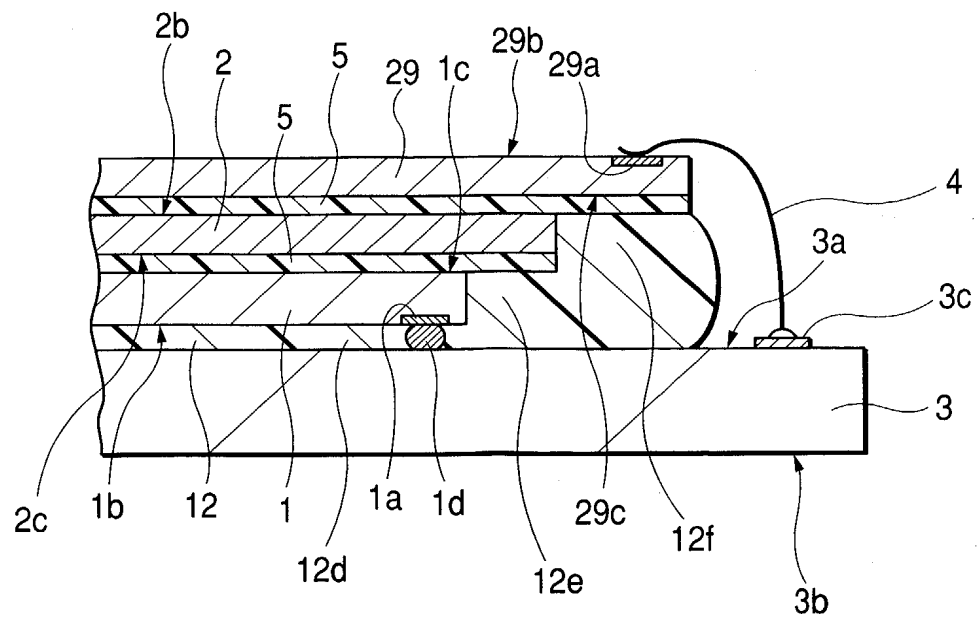


FIG. 43

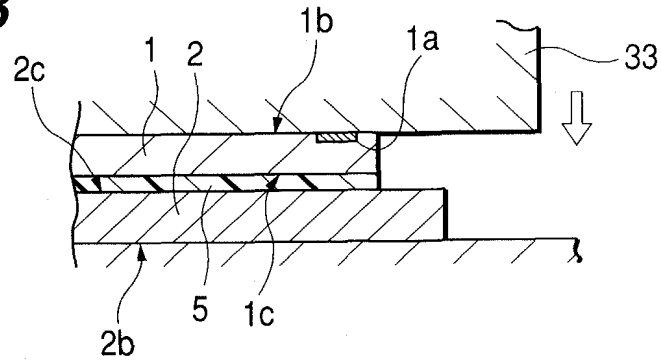


FIG. 44

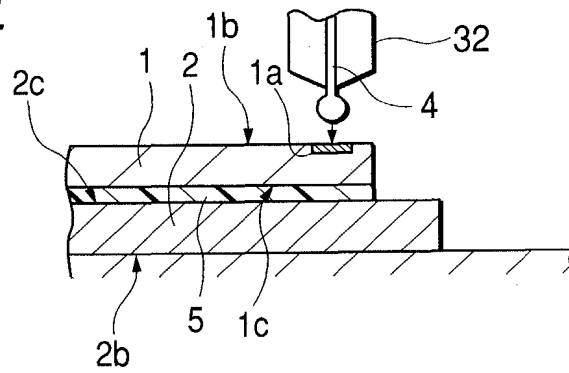
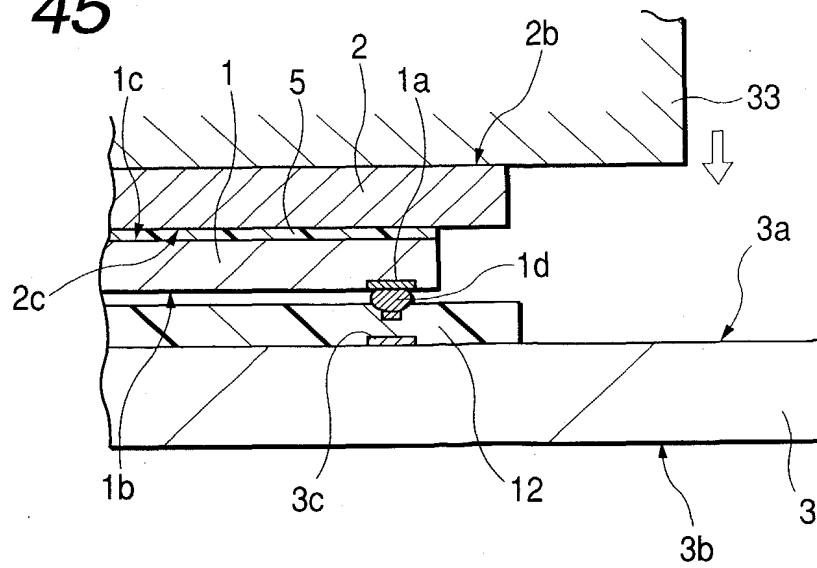


FIG. 45



This diagram illustrates a second embodiment of the device in cross-section. The main body consists of several layers labeled 1, 2, 5, 12, and 29. Layer 1 contains internal features 1a, 1b, 1c, 1d, and 1e. Layer 2 has feature 2b. Layer 5 has feature 5b. Layer 12 includes features 12d, 12e, and 12f. A central core is labeled 29, with specific regions 29a, 29b, and 29c. On the right side, there is a vertical component 33 with a downward-pointing arrow, and a horizontal base or support structure labeled 3a and 3b.

FIG. 48

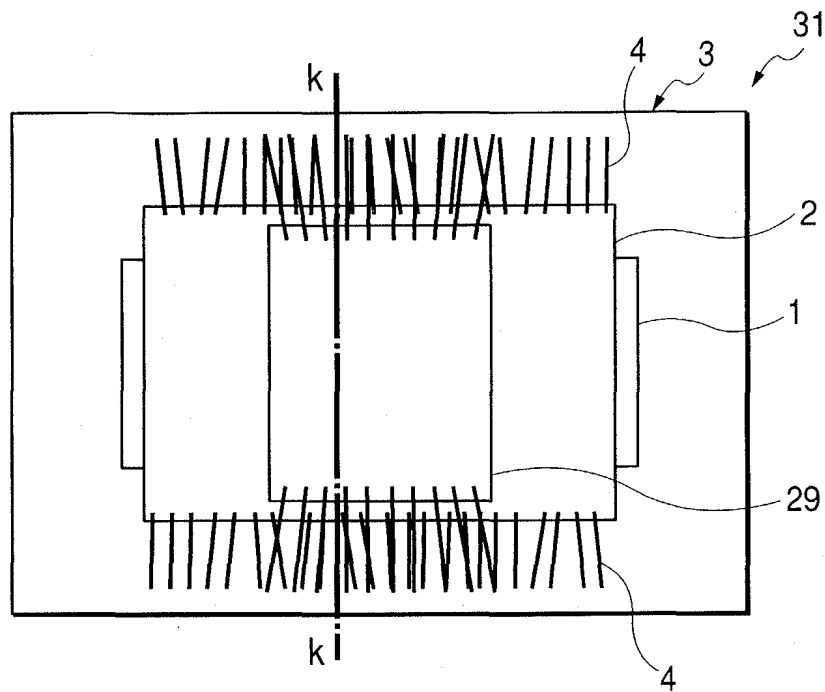
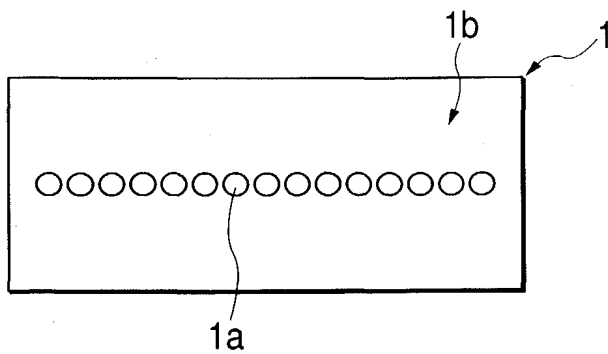


FIG. 49



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FIG. 50

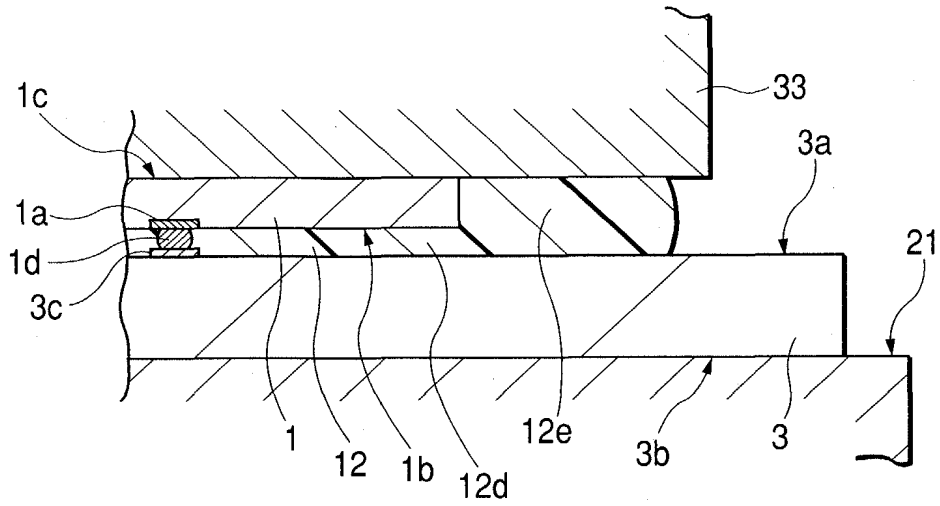
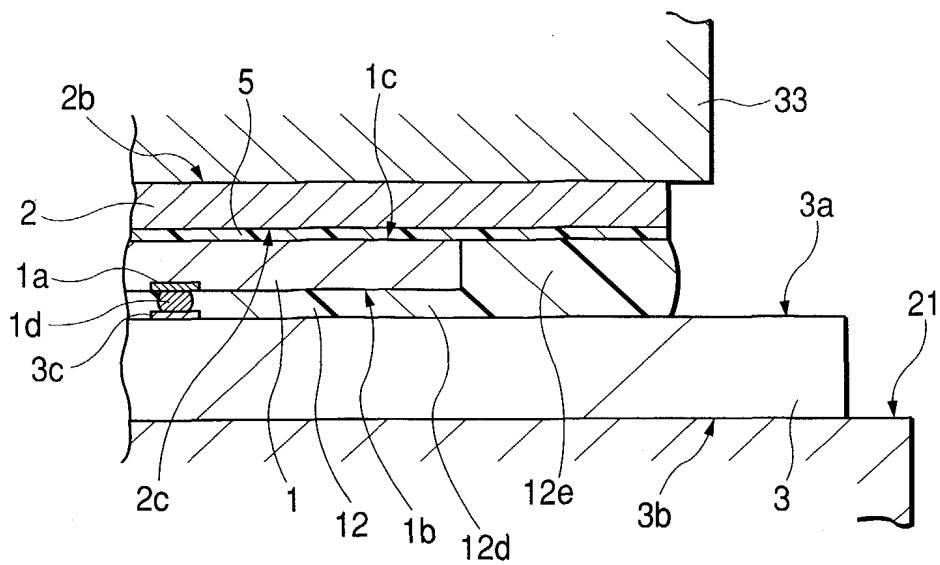


FIG. 51



[illegible]

